



Description

JMT P-channel Enhancement Mode Power MOSFET

Features

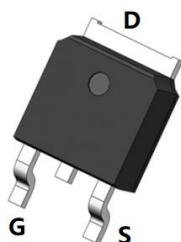
- $V_{DS} = -30V$, $I_D = -20A$
 $R_{DS(ON)} < 34m\Omega$ @ $V_{GS} = -10V$
 $R_{DS(ON)} < 50m\Omega$ @ $V_{GS} = -4.5V$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead free product is acquired

Application

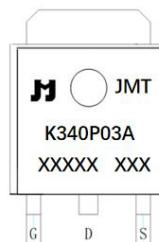
- PWM Applications
- Load Switch
- Power Management



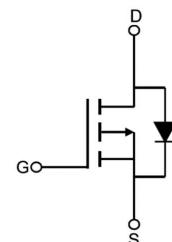
100% UIS TESTED!
100% ΔV_{ds} TESTED!



TO-252-4R top view



Marking and pin Assignment



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
JMTK340P03A	JMTK340P03A	TUBE	TO-252-4R	13inch	2500	25000

Absolute Maximum Ratings ($T_C = 25^\circ C$ unless otherwise specified)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		-30	V
V_{GSS}	Gate-Source Voltage		± 20	V
I_D	Continuous Drain Current	$T_C = 25^\circ C$	-20	A
		$T_C = 100^\circ C$	-13	A
I_{DM}	Pulsed Drain Current ^{note1}		-80	A
EAS	Single Pulsed Avalanche Energy ^{note2}		20	mJ
P_D	Power Dissipation	$T_C = 25^\circ C$	29	W
R_{eJA}	Thermal Resistance, Junction to Ambient		5.2	$^\circ C/W$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +175	°C

Electrical Characteristics ($T_J=25^\circ C$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristics						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D= -250\mu A$	-30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}= -30V, V_{GS}=0V,$	-	-	-1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0V, V_{GS}= \pm 20V$	-	-	± 100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D= -250\mu A$	-1.0	-1.5	-2.5	V
$R_{DS(on)}$ note3	Static Drain-Source on-Resistance	$V_{GS}= -10V, I_D= -7A$	-	26	34	$m\Omega$
		$V_{GS}= -4.5V, I_D= -4A$	-	36	50	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}= -15V, V_{GS}=0V,$ $f=1.0MHz$	-	982	-	pF
C_{oss}	Output Capacitance		-	135	-	pF
C_{rss}	Reverse Transfer Capacitance		-	109	-	pF
Q_g	Total Gate Charge	$V_{DS}= -15V, I_D= -4A,$ $V_{GS}= -10V$	-	10	-	nC
Q_{gs}	Gate-Source Charge		-	2	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	2.7	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}= -15V, I_D= -7A,$ $V_{GS}= -10V, R_{GEN}=2.5\Omega$	-	11	-	ns
t_r	Turn-on Rise Time		-	19	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	45	-	ns
t_f	Turn-off Fall Time		-	26	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current	-	-	-20	A	
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	-80	A	
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0V, I_S= -20A$	-	-	-1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition : $T_J=25^\circ C, V_{DD}=-15V, V_G=-10V, L=0.5mH, Rg=25\Omega, I_{AS}=-9A$

3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$

Typical Performance Characteristics

Figure 1: Output Characteristics

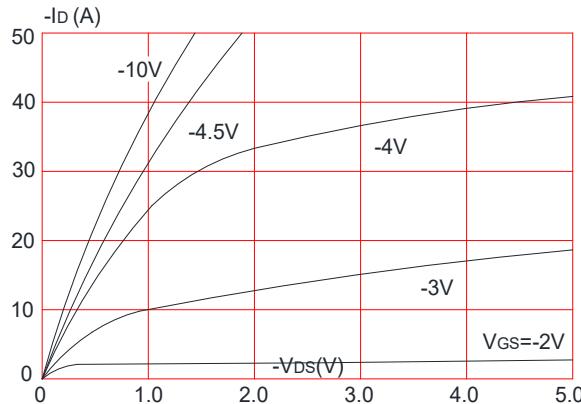


Figure 3: On-resistance vs. Drain Current

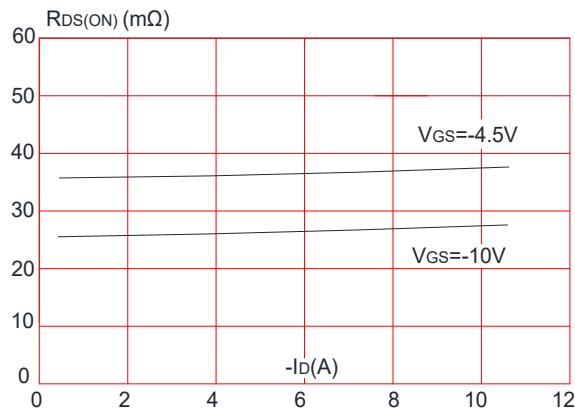


Figure 5: Gate Charge Characteristics

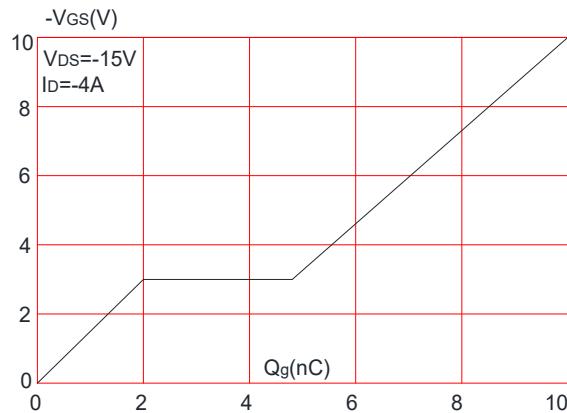


Figure 2: Typical Transfer Characteristics

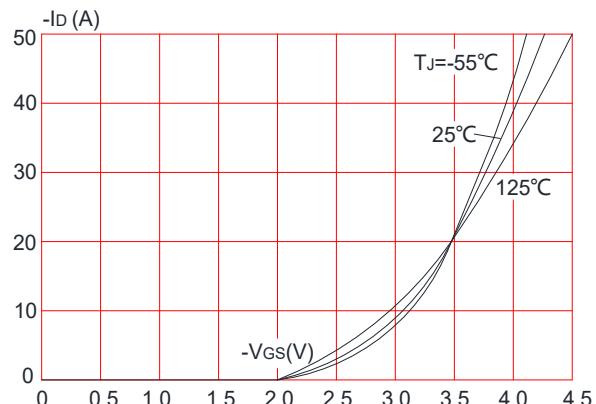


Figure 4: Body Diode Characteristics

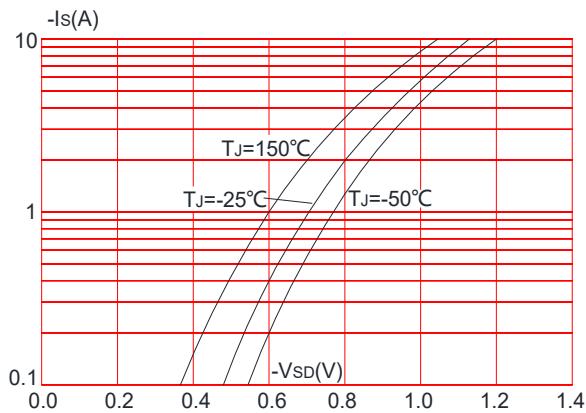


Figure 6: Capacitance Characteristics

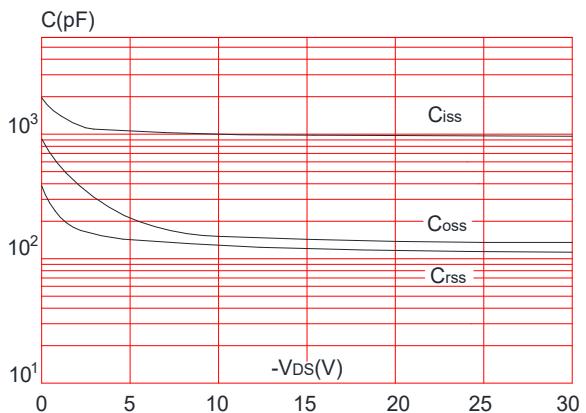


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

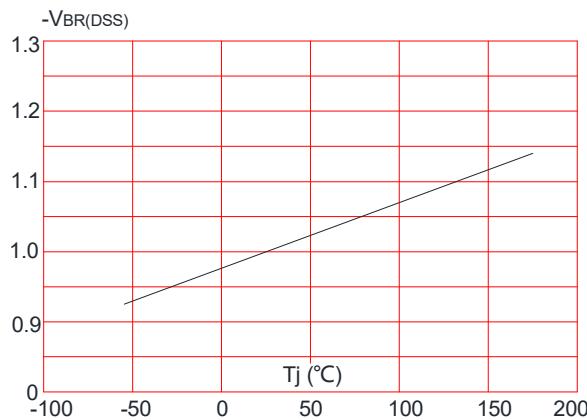


Figure 8: Normalized on Resistance vs. Junction Temperature

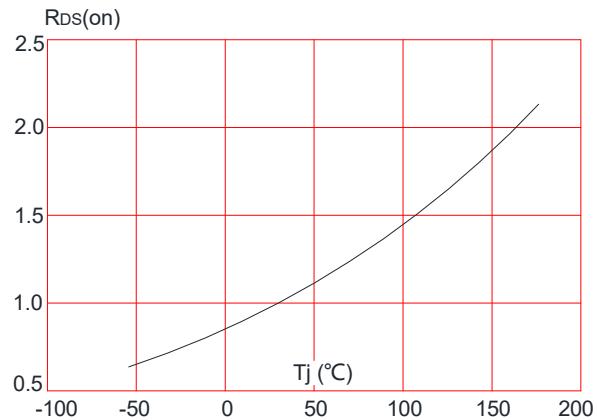


Figure 9: Maximum Safe Operating Area

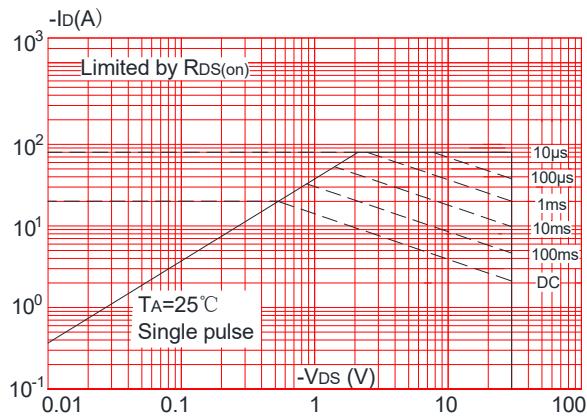


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

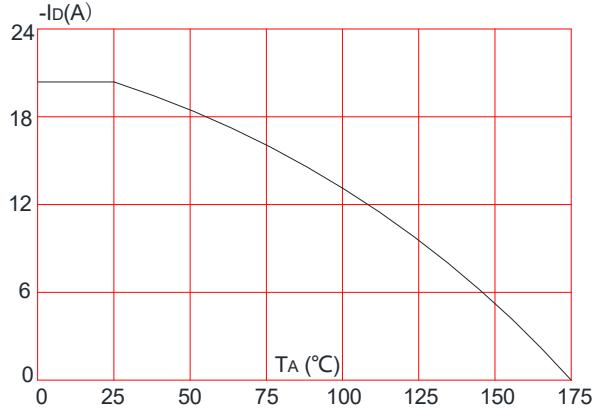
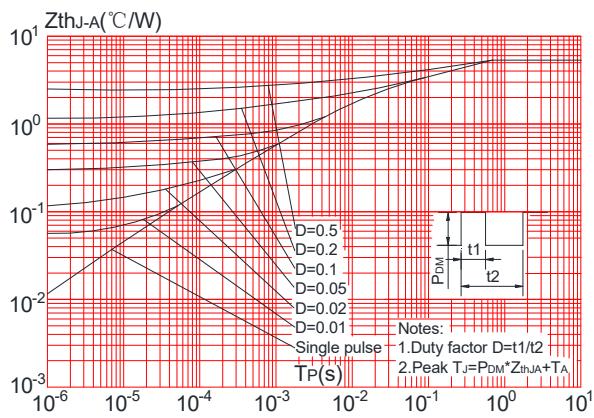
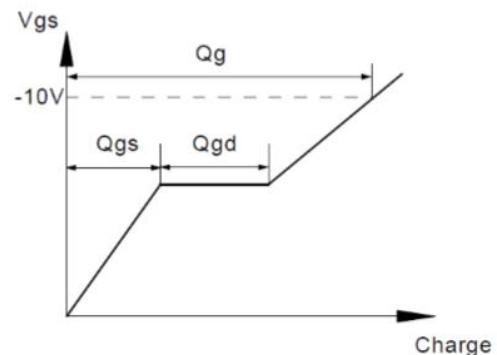
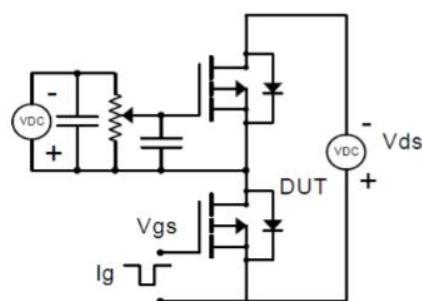


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

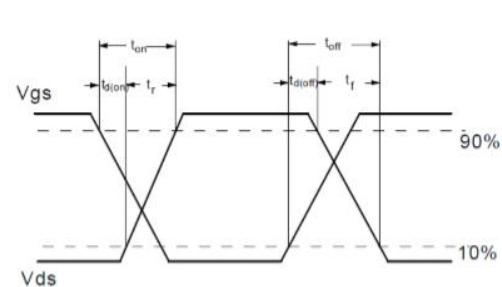
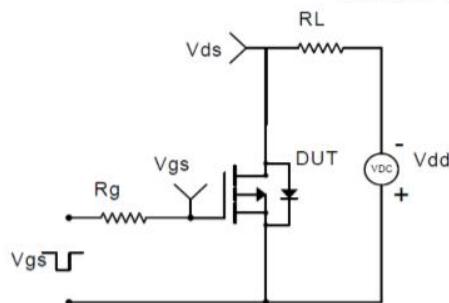


Test Circuit

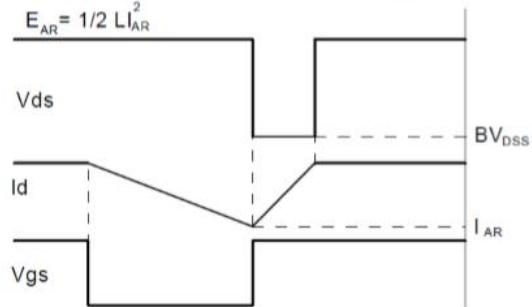
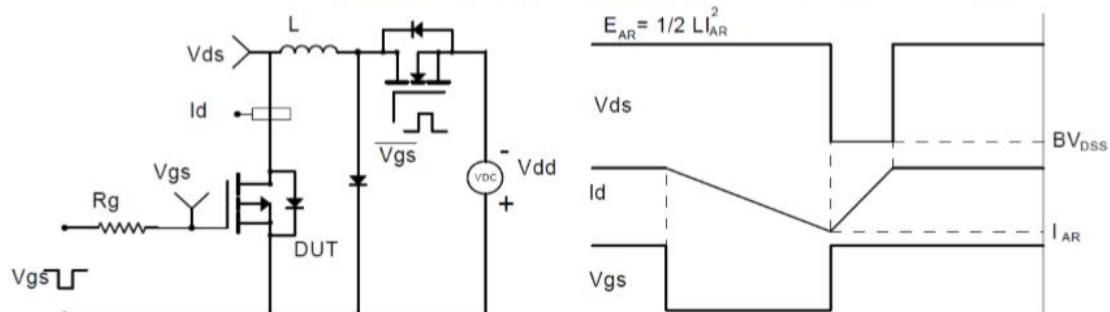
Gate Charge Test Circuit & Waveform



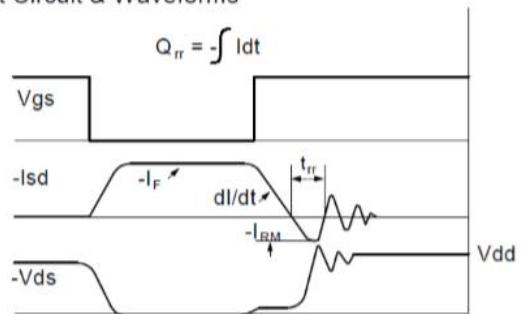
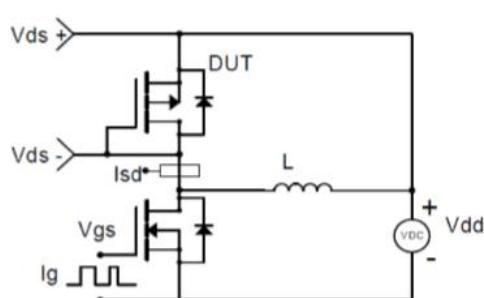
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms





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